

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Serial No.: (Divisional of U.S. Serial No. 09/322,416 which is  
a Continuation of U.S. Serial No. 09/187,617)  
Filed: July 3, 2001  
Applicant: Austin et al.  
Title: **METHOD FOR VACUUM ENCAPSULATION OF  
SEMICONDUCTOR CHIP PACKAGES**  
Our Ref. No.: NOR-865B

Cincinnati, OH

July 3, 2001

Assistant Commissioner for Patents  
Washington, D.C. 20231

**PRELIMINARY AMENDMENT**

Sir:

Prior to examination of the above-identified application, please  
amend the application as follows:

**In the Specification:**

On page 1, line 1, please insert the following: --The present  
application is a divisional of co-pending U.S. Serial No. 09/322,416, filed  
May 28, 1999, which is a continuation of U.S. Serial No. 09/187,617, filed  
November 6, 1998, the disclosures of which are hereby incorporated herein  
by reference in their entirety.--

**In the Claims:**

Please cancel claims 12-21 without prejudice or disclaimer.


Attached hereto is a marked-up version of the changes made to the claims by the current amendment. The attached page is captioned **"Version with markings to show changes made"**.

If any additional fees are necessary to complete this communication, the Commissioner is hereby authorized to charge same to Deposit Account 23-3000.

Respectfully submitted,

WOOD, HERRON & EVANS, L.L.P.

By

  
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**VERSION WITH MARKINGS TO SHOW CHANGES MADE**

**In the Specification:**

On page 1, line 1, please insert the following: --The present application is a divisional of co-pending U.S. Serial No. 09/322,416, filed May 28, 1999, which is a continuation of U.S. Serial No. 09/187,617, filed November 6, 1998, the disclosures of which are hereby incorporated herein by reference in their entirety.--

**In the Claims:**

Claims 12-21 have been canceled.